

Appl. No. 10/709,427
Amdt. dated January 16, 2006
Reply to Office action of November 08, 2005

Amendments to the Specification:

Please replace paragraph [0005] with the following amended paragraph:

5 [0005] The method of providing a bonding option is used to provide Enable, Disable, and
Input/Output options for some pins of a package. This method not only ~~makes~~ allows
users to change the hardware configuration of VLSI circuits, but also to provide detecting
and debugging of the VLSI circuits.

Please replace paragraph [0021] with the following amended paragraph:

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[0021] Please refer to Fig.4. Fig.4 illustrates the bonding option architecture 50 of the
present invention providing three connection points for the bonding pads. The bonding
option architecture 50 comprises a plurality of lead frames 52, a plurality of bonding
wires 54, a chip 56, a first package substrate 58, and a second package substrate 60. The
15 chip 56 comprises a plurality of bonding pads 62. The bonding pads 62 are set inside the
chip 56 and surround the chip 56, providing the outlets of input/output ends of the chip 56.
The lead frames 52 distributed around and outside the chip 56 are connected to the
bonding pads 62 inside the chip 56 through bonding wires 54. The bonding pads 62 are
like the connection points which connect the inside circuit of the chip 56 to the outside
20 system while the lead frames 52 are like the connection points which connect the outside
system to inside circuit of the chip 56. The bonding option architecture 50 lets the
input/output signals of the chip ~~to~~ communicate with outside circuitry and provides chip
testing.

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